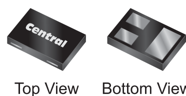
Material Composition Specification

SOT-883VL Case



Device average mass . . . . **0.614 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	5.7%	0.035	Si	7440-21-3	5.7%	0.035	57,003
bond wire	gold	1.63%	0.01	Au	7440-57-5	1.63%	0.01	16,287
leadframe	Cu alloy	42.35%	0.26	Cu	7440-50-8	40.72%	0.25	407,166
				Ni	7440-02-0	1.29%	0.0079	12,866
				Si	7440-21-3	0.28%	0.0017	2,769
				Mg	7439-95-4	0.07%	0.0004	651
die attach	silver epoxy	0.9%	0.0055	epoxy resin	Proprietary	0.18%	0.0011	1,792
				Ag	7440-22-4	0.72%	0.0044	7,166
encapsulation*	EMC GREEN	49.02%	0.301	silica (fused)	60676-86-0	41.53%	0.255	415,309
				epoxy resin	29690-82-2	3.75%	0.023	37,459
				phenol resin	9003-35-4	1.3%	0.0080	13,029
				carbon black	1333-86-4	0.16%	0.001	1,629
				metal hydroxide	1309-42-8	2.28%	0.014	22,801
plating	Ni/Pd/Au	0.41%	0.0025	Ni	7440-02-0	0.36%	0.0022	3,583
				Pd	7440-05-3	0.03%	0.0002	326
				Au	7440-57-5	0.02%	0.0001	163

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R0 (20-October 2014)